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71369-25-01

Attorney's Do. No. 4234-9

DECLARATION FOR PATENT APPLICATION

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor of the subject matter which is claimed and for which a patent is sought on the invention entitled **METHOD OF MANUFACTURING UNVULCANIZED ADHESIVE WATERPROOF SHEET AND CONSTRUCTION METHOD USING THE SAME**, the specification of which:

- ☐ is attached hereto.
- ☒ was filed on November 13, 2000 as Application Serial No. 09/712,029
- ☐ and was amended on _____
- ☐ with amendments through _____

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations, Sec. 1.56.

I hereby claim foreign priority benefits under Title 35, United States Code, Sec. 119(a)-(d) of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

Prior Foreign Application(s)

99-50626
(Number)

Korea
(Country)

15 November 1999
(Day/Month/Year Filed)

Priority Claimed

☒ Yes
☐ No

I hereby claim the benefit under Title 35, United States Code, Sec. 119(e) of any United States provisional application listed below:

Provisional Application No.

Filing Date

I hereby claim the benefit under Title 35, United States Code, Sec. 120 of any United States application(s), or Sec. 365(c) of any PCT International application designating

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the United States, listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States or PCT International application in the manner provided by the first paragraph of Title 35, United States Code, Sec. 112. I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations, Sec. 1.56 which became available between the filing date of the prior application and the national or PCT international filing date of this application:

(App. Serial No.)

(Filing Date)

(Status -patented, pending, etc.)

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Full name of sole or first inventor:

Dae-Woo LEE

Inventor's signature:

Dae Woo, Lee

MAY 14, 2001
(Date)

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